## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:
Chii-Ming WU, et al.

Serial No.: 10/657,505

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Filed: September 8, 2003

For: Method of Manufacturing a Contact
Interconnection Layer Containing a Metal and
Nitrogen by Atomic Layer Deposition for
Deep Sub-Micron Semiconductor
Technology

Sconfirmation No. 9336

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Examiner: Geyer, Scott B.

Attorney Docket No.:
TS01-1247 / 24061.406

Commissioner for Patents Mail Stop Amendment P.O. Box 1450 Alexandria, VA 22313-1450

## **AMENDMENT**

Sir:

The Commissioner is hereby authorized to charge Haynes and Boone, LLP's Deposit Account No. 08-1394. in the amount of \$120 for one-month extension of time for consideration of the present paper. If any other fees are necessary, including additional extension of time fees, the extension of time is hereby requested and the Commissioner is hereby authorized to charge any fees to Haynes and Boone, LLP's Deposit Account No. 08-1394.

In response to the Office Action of September 27, 2006, please amend the above-identified application as follows:

Listing of Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 9 of this paper.